

MACOM Technology Solutions Inc.
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Lowell, Massachusetts 01851
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December 15, 2023

Richardson RFPD, Inc.
1950 S. Batavia Ave, Suite 100
Geneva, Illinois 60134

ATTN: Quality/Purchasing Manager

Subject: Substrate plating change to standard process

PCN #: PCN-01687

Dear Valued Customer:

The goal of MACOM Technology Solutions is to continually deliver high quality products and services that meet our customers' needs. We strive to offer products that are industry leading in terms of performance, delivery and value.

In accordance with these goals, this communication is to inform you that MACOM is making a plating change to the ceramic substrate used in the following devices.

MSW2040-204
MSW2041-204
MSW2041-204-R
MSW2041-204-T
MSX0034-204-R

You are receiving this notice because you have purchased the above product in the past two years.

Please contact your local sales representative if you have any questions or require additional information.

Sincerely,

Thomas Galluccio
Product Manager
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PCN Number: PCN-01687		PCN Date: December 15, 2023	
Title: Metallization/Plating change			
Date of change: December 2023		Estimated Sample Availability/Qualification Completion: On request	
Proposed last Ship Date:			
Change Classification:		Major ☐ Minor ☒	
Change Type:			
Assembly Site ☐		Design ☐	
Test Site ☐		Electrical Specification ☐	
Test Process ☐		Assembly Process ☐	
		Mechanical Specification ☐	
		Assembly Materials ☒	
		Packing/Shipping/Labeling ☐	
PCN Details			
Description of Change:			
Updating the plating to standardize processing. Changes shown below. Current Metallization: METALLIZATION: FRONT AND BACK METAL (750-1500) Å TiW.(SPUTTERED) (5000±500) Å Ni. (SPETTERED) -FRONTSIDE: 50µ INCHES MIN. Au. (PLATED) -BACKSIDE: (10-20) µ INCHES Au (PLATED) New Metallization: - TOPSIDE METAL A1: TIW: 1000-1500Å (SPUTTERED) NI: 7-9uIN (SPUTTERED) AU: 55-65uIN (SPUTTERED) - TOPSIDE METAL A2: CU: 18-22uIN (SPUTTERED) CU: 800uIN MIN. (PLATED) NI: 40-80uIN (PLATED) AU: 30uIN MAX. (PLATED) - BACKSIDE METAL: TIW: 1000-1500Å (SPUTTERED) NI: 18-22uIN (SPUTTERED) AU: 16-18uIN (SPUTTERED)			
Reason for Change:			
Standardize ceramic substrate metallization and plating across this product portfolio.			
Products Affected:			
See front page			
Anticipated impact on Fit, Form, Function:			
There will be no impact on fit, form, function, or reliability by this change.			
Changes to product identification resulting from this PCN:			
None.			
Material Declaration updated due to this change:		Yes ☒ No ☐	